	·,			
	•		TMENT OF COM ent and Tradema	
SEARCH REQUEST	FORM Reiss	sue ap	plication	<i>H</i>
Requestor's Name: Marianne Padgett Nur	ial mber: <u>09/12</u>	17,55	/	(
Date: $\frac{5/1/99}{}$ Phone: $\frac{308 - 23}{}$	36 Art U	nit: <u>/ 7</u>	62	
Search Topic: Please write a detailed statement of search topic. Describe specifically as poss that may have a special meaning. Give examples or relevant citations, authors a copy of the sequence. You may include a copy of the broadest and/or most	keywords, etc., if know	o be searched. n. For seque	Define any to nces, please at	erms tach
Litigation search	fir			
U.S. P.N. 5, 571,57	/		e Jane	
SN,08/259,584	3	N.		
				·
्राप्ति । en				
				Confidence:
				بطيت

STA	FF USE ONLY	,
Date completed: 5/12/99	208-4290 Search Site	Vendors
Searcher: — YOUNGER THERE	STIC	IG Suite
Terminal time:	CM-1	STN
Elapsed time:	Pre-S	Dialog
CPU time:	Type of Search	APS
Tôtal time:	N.A. Sequence	Geninfo
Number of Searches:	A.A. Sequence	SDC
Number of Databases:	Structure	DARC/Questel
	Bibliographic	Other
	•	Helis_

Orbit

FILE LITALERT

ELAPSED TIME ON ORBIT: 0.01 HRS.

YOU ARE NOW CONNECTED TO LITALERT.
CURRENT THRU WEEKLY UPDATE (9918)

SS 1?

NBR US5571571/PN

SELECT LIST DEFAULT:

SELECT#	RESULTS	TERM	
			_

1 1 US5571368/PN 2 3 US5571471/PN 3 1 US5571599/PN 4 1 US5571961/PN

US5572570/PN

5 UP N OR DOWN N?

KATHLEEN FULLER STIC LIBRARY 308-4290



YOU ARE NOW CONNECTED TO <u>LEGSTAT</u>. CURRENT THRU WEEKLY UPDATE (9917)

CONNECT HOUR COST AND RECORD PRICE REDUCED - SEE NEWSDOC N283.

```
SS 1?
NBR US5571571/PN
SELECT LIST DEFAULT:
SELECT# RESULTS
                  TERM
               1
                  US5571569/PN
      6
      7
               1
                  US5571570/PN
      8
               1
                  US5571571/PN
      9
               1
                  US5571572/PN
     10
               1
                  US5571573/PN
UP N OR DOWN N?
SEL 8
SS 1 RESULT (1)
SS 2?
PRT FU
-1- (LEGSTAT)
   - US 5571571 [US5571571]
PN
DT - US-P
ACT - 94.06.14 US/AE-A
      APPLICATION DATA (PATENT)
       {US 259584/94 [94US-259584] 94.06.14}
ACT - 94.08.22 US/AS02
      ASSIGNMENT OF ASSIGNOR'S INTEREST
      APPLIED MATERIALS, INC. LEGAL AFFAIRS DEPARTMENT 3050 BOWERS AVENUE M/S
      #0934 SA * MUSAKA, KATSUYUKI : 19940810; MIZUNO, SHINZUKE : 19940725
ACT - 96.11.05 US/A
      PATENT
ACT - 99.03.02 US/RF
      REISSUE APPLICATION FILED
      981105
UP - 9918
SS 2?
```



YOU ARE NOW CONNECTED TO PAST. COVERS 1973 THRU WEEKLY UPDATE (9918)

SS 1? NBR US5571571/PN

```
SELECT LIST DEFAULT:
SELECT# RESULTS TE
```

/PN
/PN
/PN
/PN
/PN
/PI /PI /PI

SEL 13

SS 1 RESULT (1)

SS 2? PRT FU

-1- (PAST) AN - 9909-001269 PN - US5571571 DT - A (UTILITY) OG - 99.03.02

CO - REA

ACT - REISSUE APPLICATION FILED SH - REISSUE APPLICATION FILED

SS 2?

```
File 345:Inpadoc/Fam. & Legar Stat 1999/UD=9917
       (c) 1999 European Patent Office
      Set Items Description
          ----
? S PN=US 5571571
              1 PN=US 5571571
      S1
? T1/9/1
 1/9/1
DIALOG(R) File 345: Inpadoc/Fam. & Legal Stat
(c) 1999 European Patent Office. All rts. reserv.
12226506
Basic Patent (No, Kind, Date): JP 7022316 A2 950124
                                                  <No. of Patents: 002>
PATENT FAMILY:
JAPAN (JP)
  Patent (No, Kind, Date): JP 7022316 A2 950124
    THIN FILM FORMATION OF SEMICONDUCTOR DEVICE (English)
    Patent Assignee: APPLIED MATERIALS INC
   Author (Inventor): MIZUNO SHINSUKE; MUTSUHIRA KATSUYUKI
    Priority (No, Kind, Date): JP 93145070 A 930616
    Applic (No, Kind, Date): JP 93145070 A
    IPC: * H01L-021/205
    CA Abstract No: ; 123(06)072326S
    Derwent WPI Acc No: ; C 95-095327
    Language of Document: Japanese
UNITED STATES OF AMERICA (US)
  Patent (No, Kind, Date): US 5571571 A 961105
    METHOD OF FORMING A THIN FILM FOR A SEMICONDUCTOR DEVICE Method of
      forming a thin film for a semiconductor device (English)
    Patent Assignee: APPLIED MATERIALS INC (US)
   Author (Inventor): MUSAKA KATSUYUKI (JP); MIZUNO SHINZUKE (JP)
    Priority (No, Kind, Date): US 259584 A 940614; JP 93145070 A
      930616; US 184331 B2 940119
   Applic (No, Kind, Date): US 259584 A
                                           940614
    National Class: * 427574000; 427563000; 427575000; 427579000
    IPC: * H05H-001/02; H05H-001/30; H05H-001/24
    CA Abstract No: * 123(06)072326S; 125(26)344926R; 125(26)344926R
    Derwent WPI Acc No: * C 95-095327
    Language of Document: English
UNITED STATES OF AMERICA (US)
                                    xt):
                                           PRIORITY (PATENT)
                                    45070 A 930616
                                           PRIORITY
```

Lega]	l Status	(No, Ty	pe,Date,	Code	e,Text):		
US	5571571	P	930616	US	AA	PR	IORITY
				JP	93145070	A	93061
US	5571571	P	940119	US	AA	PR	IORITY
				US	184331	B2	940119
US	5571571	P	940614	US	AE	AP	PLICATI

APPLICATION DATA (PATENT) (APPL. DATA (PATENT)) US 259584 A 940614 US 5571571 Ρ 961105 US A PATENT US 5571571 Ρ 990302 US RF REISSUE APPLICATION FILED

(REISSUE APPL. FILED)

981105



Please ENTER the NAME of the file you want to search. To see a description of a file, type its page number and press the ENTER key.

FILES - PAGE 1 of 6 (NEXT PAGE for additional files)

NAME PG DESCRIP NAME PG DESCRIP

--- CASES & ADMINISTRATIVE DECISIONS--IPOMNI 1 Int Prop Cases & Reg Matl 1 FEDCTS, PTO, ITC, ALLREG 1 FEDCTS, PTO & ITC PTOMNI CASES FEDCTS 2 Patent cases from Fed. Cts. 2 Ct Customs & Patent Appeals CCPA 2 Patent cases from Fed. Cir. CAFC PTO 2 PATAPP & COMMR -----SECONDARY SOURCES-----CHISUM 5 Chisum on Patents

5 Manual of Patent Exam Proc MPEP PTORUL 5 Patent Office Rules

MILGRM 5 Milgrim on Trade Secrets 5 Intell Prop Law Nwltrs /IPLTR 5 Intell Prop Law Rev Articles IPLR * Selected coverage 1/15/71 to 12/3/74

-----PATENTS-----4 UTIL, DESIGN, PLANT, SIR, ALL

REEXAM & REISS

4 Full Text Patents from 1971*

UTIL DESIGN 4 Full Text Patents from 1976 4 Full Text Patents from 1976 PLANT REEXAM 4 Reexamination Certificates

REISS 4 Reissue Patents

SIR 4 Defensive Publications

ASSIGN 4 Assignee

ABSTCL 4 Abstracts & Claims

I listing from all these database

5,571,571

<=2> GET 1st DRAWING SHEET OF 9

Nov. 5, 1996

Method of forming a thin film for a semiconductor device

REISSUE: Reissue Application filed Nov. 5, 1998 (O.G. Mar. 2, 1999) Ex. Gp.:

1762; Re. S.N. 09/187,551

INVENTOR: Musaka, Katsuyuki, Sakae, Japan

Mizuno, Shinzuke, Narita, Japan

ASSIGNEE-AT-ISSUE: Applied Materials, Inc., Santa Clara, California (02)

APPL-NO: 259,584

FILED: Jun. 14, 1994

FOR-PRIOR:

Jun. 16, 1993 Japan 5-145070

REL-US-DATA:

Continuation-in-part of Ser. No. 184,331, Jan. 19, 1994 now abandoned

INT-CL: [6] H05H 1#02; H05H 1#30; H05H 1#24

US-CL: 427#574; 427#563; 427#575; 427#579; 438#784; 438#789;

CL: 427;438;

SEARCH-FLD: 427#563, 574, 578, 579, 575

REF-CITED:

U.S. PATENT DOCUMENTS

<=3>	4,282,267	8/1981	*	Kuyel	427#563
<=4>	4,461,783	7/1984	*	Yamazaki	427#563
<=5>	4,668,365	5/1987	*	Foster et al.	204#192.23
<=6>	4,778,721	10/1988	*	Sliemers et al.	427#578
<=7>	4,818,563	4/1989	*	Ishihara et al.	427#574
<=8>	4,872,947	10/1989	*	Wang et al.	427#574
<=9>	4,894,352	1/1990	*	Lane et al.	437#238
<=10>	5,013,691	5/1991	*	Lory et al.	437#238

Pa No. 5571571, *

<=1 î >	5,206,060	4/1993	*	Balian et al.	427#578
<=12>	5,223,457	6/1993	*	Mintz et al.	427#574
<=13>	5,275,977	1/1994	*	Otsubo et al.	437#228
<=14>	5,286,518	2/1994	*	Cain et al.	427#574
<=15>	5,288,518	2/1994	*	Homma	427#574
<=16>	5,356,722	10/1994	*	Nguyen et al.	427#574
<=17>	5,429,995	7/1995	*	Nishiyama et al.	427#563
<=18>	5,462,899	10/1995	*	Ikeda	427#563
<=19>	5,492,736	2/1996	*	Laxman et al.	427#579

FOREIGN PATENT DOCUMENTS

573911	12/1993	*	European Patent Office (EPO)	H01#L2.1314
			World Intellectual Property	
92/20833	11/1992	*	Organization (WIPO)	C23#C1.600

OTHER PUBLICATIONS

Abstract of JP63062238 from Patent Abstracts of Japan vol. 12, No. 285 (E-642) published Mar. 1988 to Tsunetoshi et al.

Webb ef al, "Silicon Dioxide Films produced . . . " Oric, 2nd Int'l ULSI Conf. 1989 No month.

Yu et al "Step Coverage Study of PETEOS . . . " VMIC Conf. 1990 IEEE, Jun. 12-13, 1990.

PRIM-EXMR: Padgett, Marianne

LEGAL-REP: Morris; Birgit E.

Einschlag; Michael B.

CORE TERMS: silicon, film, oxide, gas, chamber, strip, plasma, fluorine, deposition, electrode, frequency, layer, aluminum, conductive, substrate, semiconductor, deposited, spacing, power source, width, graph, gases, voids, atomic, concentration, deposit, halogen, precursor, sidewall, ratio

ABST:

A method of forming conformal, high quality silicon oxide films that can be deposited over closely spaced, submicron lines and spaces without the formation of voids, comprises forming a plasma of TEOS and a selected halogen-containing gas in certain ratios. By proper control of the energy sources that create the plasma, the proper selection of the halogen-containing gas and selection of other processing parameters, high deposition rates can also be achieved.

NO-OF-CLAIMS: 10

EXMPL-CLAIM: <=20> 1

NO-OF-FIGURES: 34

NO-DRWNG-PP: 9

PARCASE: This application is a continuation-in-part of application Ser. No. 08/184,331 filed Jan. 19, 1994, now abandon, entitled "A METHOD OF FORMING A THIN FILM FOR A SEMICONDUCTOR DEVICE".

SUM:

The present invention relates to a method of forming a thin film for a semiconductor device. More particularly, this invention relates to a plasma-enhanced chemical vapor deposition (hereinafter PECVD) method for forming a silicon oxide thin film on a semiconductor substrate.

BACKGROUND OF THE INVENTION